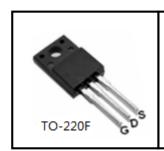
#### **500V N-Channel MOSFET**

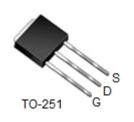
#### **FEATURES**

- Fast switching
- 100% avalanche tested
- Improved dv/dt capability

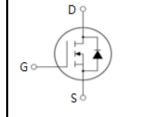
#### **APPLICATIONS**

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply (UPS)
- Power Factor Correction (PFC)









Device Marking and Package Information				
Device	Package	Marking		
CST1N50DLU	TO-251	CST1N50DLU		
CST1N50DLD	TO-252	CST1N50DLD		
CST1N50DLF	TO-220F	CST1N50DLF		

<b>Absolute Maximum Ratings</b> $T_C = 25^{\circ}C$ , unless otherwise noted						
Parameter	Symbol	Value			Unit	
raiametei		TO-220F	TO-251	TO-252		
Drain-Source Voltage (V <sub>GS</sub> = 0V)	V <sub>DSS</sub>	500		V		
Continuous Drain Current	I <sub>D</sub>	1		А		
Pulsed Drain Current (note1)	I <sub>DM</sub>	4		А		
Gate-Source Voltage	V <sub>GSS</sub>	±25		V		
Single Pulse Avalanche Energy (note2)	E <sub>AS</sub>	4		mJ		
Avalanche Current (note1)	I <sub>AS</sub>	0.9		А		
Repetitive Avalanche Energy (note1)	E <sub>AR</sub>	2.4		mJ		
Power Dissipation (T <sub>C</sub> = 25°C)	P <sub>D</sub>	15	1	12	W	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55~+150		°C		

Thermal Resistance					
Davanatas	Symbol	Value			l locit
Parameter		TO-220F	TO-251	TO-252	Unit
Thermal Resistance, Junction-to-Case	R <sub>thJC</sub>	10.3	8.3		°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>thJA</sub>	62.5	60		30/44

Specifications T <sub>J</sub> = 25°C, unless otherwise noted								
Parameter	Symbol	Test Conditions	Value			Unit		
		rest containens	Min.	Тур.	Max.	O.III.		
Static								
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_{D} = 250\mu A$	500			V		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 500V, V_{GS} = 0V, T_{J} = 25^{\circ}C$			1	μΑ		
Gate-Source Leakage	$I_{\rm GSS}$	$V_{GS} = \pm 30V$			±100	nA		
Gate-Source Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2.2		3.2	V		
Drain-Source On-Resistance (Note3)	R <sub>DS(on)</sub>	$V_{GS} = 10V, I_D = 0.4A$		9	11	Ω		
Dynamic								
Input Capacitance	C <sub>iss</sub>			88		pF		
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0V,$ $V_{DS} = 25V,$		10				
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1.0MHz		2.5				
Total Gate Charge	$Q_g$	$V_{DD} = 400V, I_{D} = 0.8A,$ $V_{GS} = 10V$		4.5		nC		
Gate-Source Charge	$Q_{gs}$			0.6				
Gate-Drain Charge	$Q_{gd}$	93 -		2.5				
Turn-on Delay Time	t <sub>d(on)</sub>	$V_{DD} = 250V, I_{D} = 0.8A,$ $R_{G} = 25 \Omega$		32				
Turn-on Rise Time	t <sub>r</sub>			5.8				
Turn-off Delay Time	t <sub>d(off)</sub>			42		ns		
Turn-off Fall Time	t <sub>f</sub>			34				
Drain-Source Body Diode Character	istics							
Continuous Body Diode Current	I <sub>s</sub>				1			
Pulsed Diode Forward Current	I <sub>SM</sub>	T <sub>C</sub> = 25 °C			4	A		
Body Diode Voltage	$V_{SD}$	$T_J = 25^{\circ}\text{C}, I_{SD} = 0.4\text{A}, V_{GS} = 0\text{V}$			1.4	V		
Reverse Recovery Time	t <sub>rr</sub>	$V_{GS} = 0V, I_{S} = 0.8A,$		480		ns		
Reverse Recovery Charge	Q <sub>rr</sub>	di <sub>F</sub> /dt =100A /µs		224		nC		

#### Notes

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature
- 2. L=10mH,  $V_{DD}$  = 50V,  $R_G$  = 25  $\Omega$ , Starting  $T_J$  = 25  $^{\circ}C$
- 3. Pulse Test: Pulse width ≤ 300µs, Duty Cycle ≤ 1%

#### **Typical Characteristics** $T_J = 25^{\circ}C$ , unless otherwise noted

Figure 1. Output Characteristics (T<sub>J</sub> = 25°C)

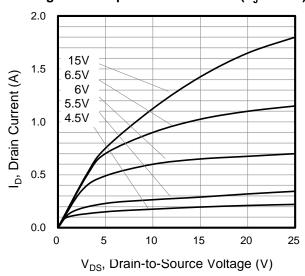


Figure 3. Drain Current vs. Temperature

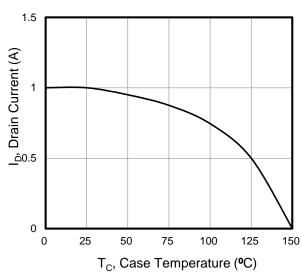


Figure 5. Transfer Characteristics

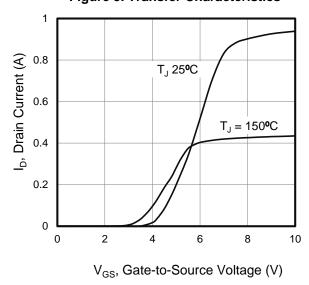
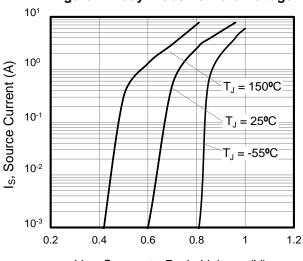


Figure 2. Body Diode Forward Voltage



V<sub>SD</sub>, Source-to-Drain Voltage (V)

Figure 4. Power Dissipation vs. Temperature TO-251,TO-252

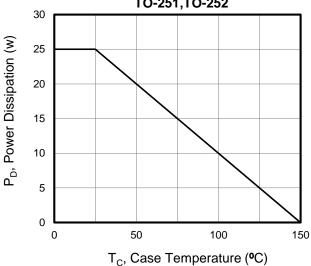
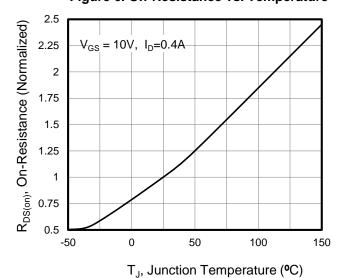


Figure 6. On-Resistance vs. Temperature



#### **Typical Characteristics** $T_J = 25^{\circ}\text{C}$ , unless otherwise noted

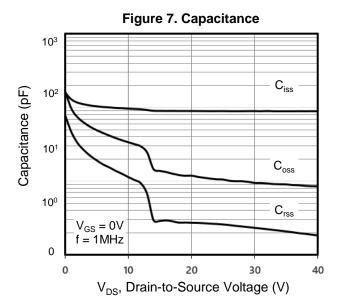


Figure 8. Gate Charge

10

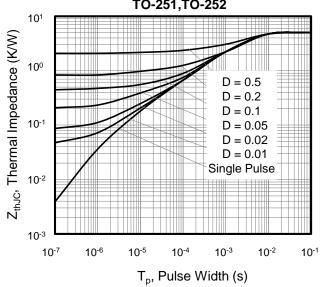
(A) about 10

(B) about 10

(C) about 10

(C)

Figure 9. Transient Thermal Impedance TO-251,TO-252



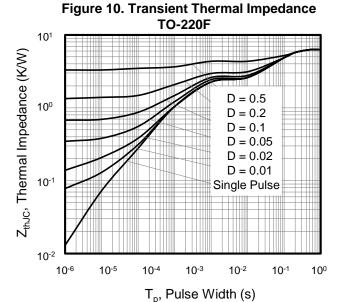


Figure A: Gate Charge Test Circuit and Waveform

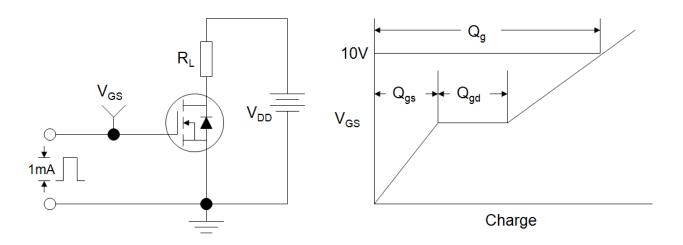


Figure B: Resistive Switching Test Circuit and Waveform

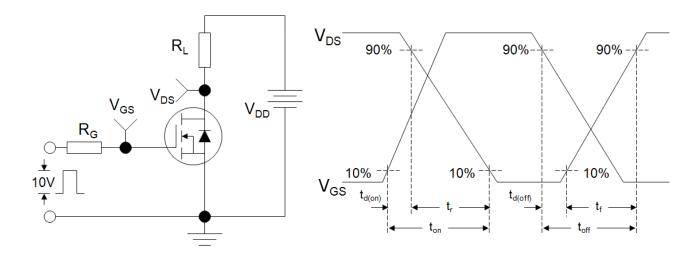
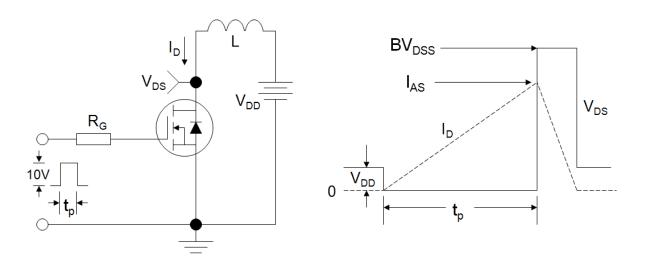
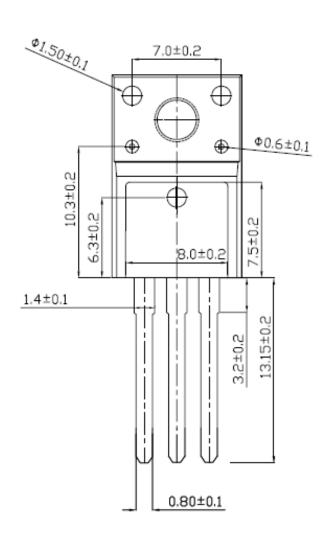
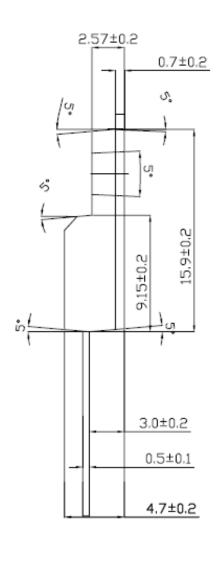


Figure C: Unclamped Inductive Switching Test Circuit and Waveform

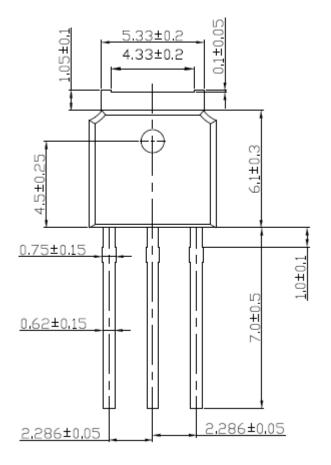


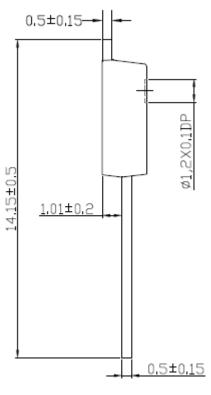
#### **TO-220F**

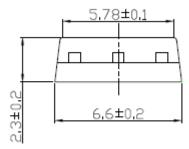




TO-251

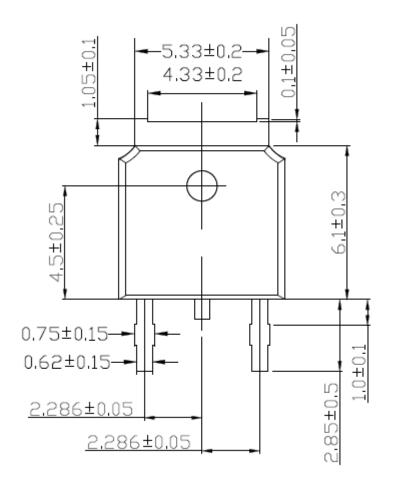


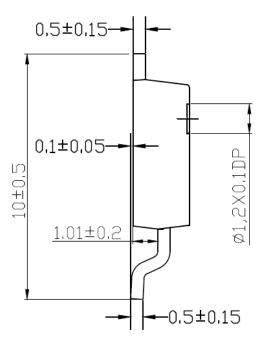


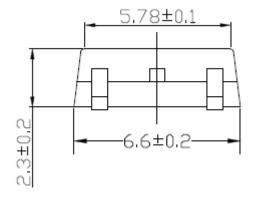




### **TO-252**









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